



SPECIFICATION FOR APPROVAL

产品规格承认书

SMD POWER INDUCTOR

功率电感

CUSTOMER.

MODEL NO.

MTF1050-100M

CUSTOMER'S PART NO.

PWPG105-100M

LILE NO.

DATE.

2021.12.06

REVISION.

A0

CUSTOMER APPROVE

DATE:

DRAWING

DRAWN BY

CHECK BY

APPROVAL BY

DATE: 2021.12.06



深圳市迈翔科技有限公司

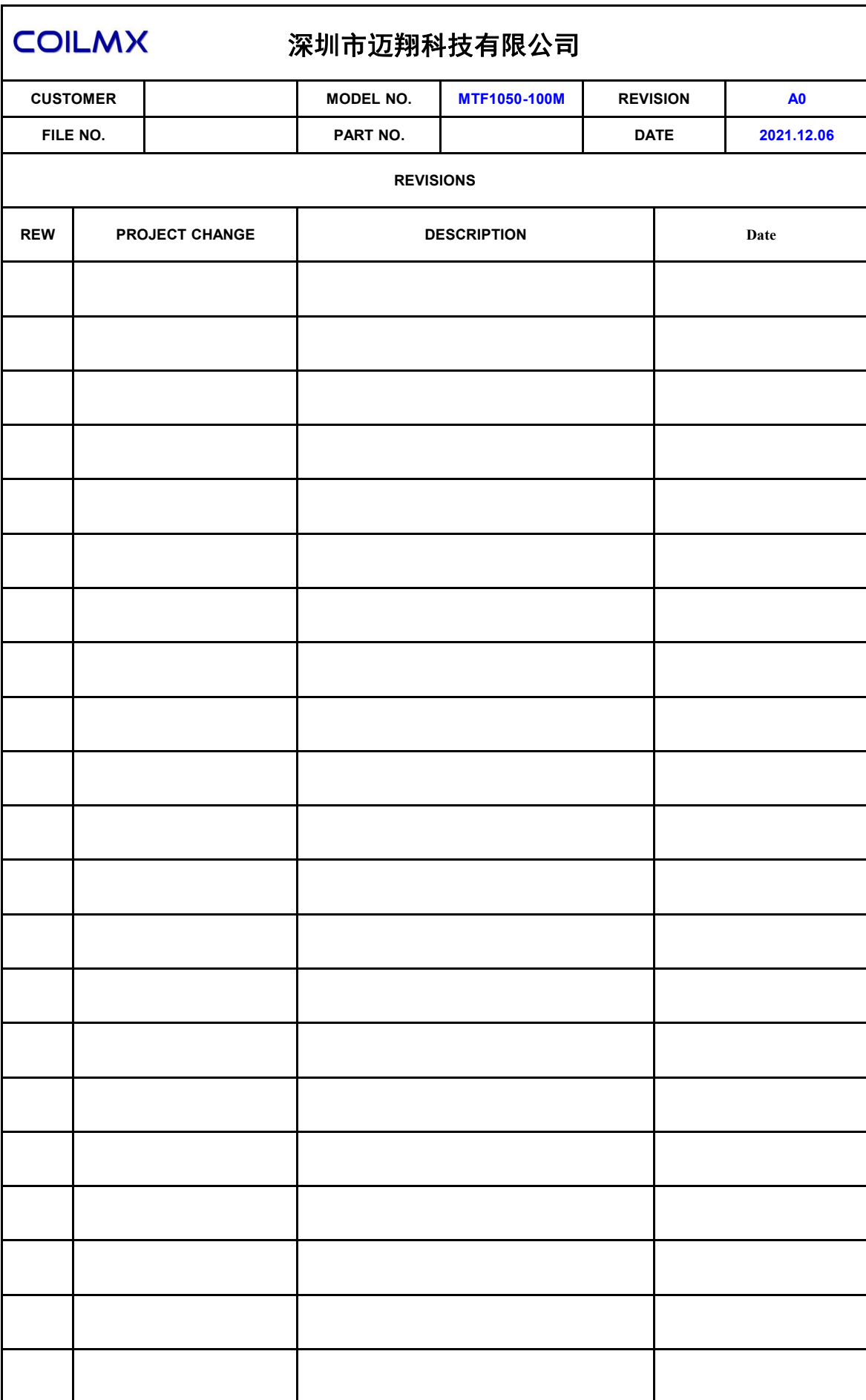
SHENZHEN MOTTO TECHNOLOGY Co., Ltd

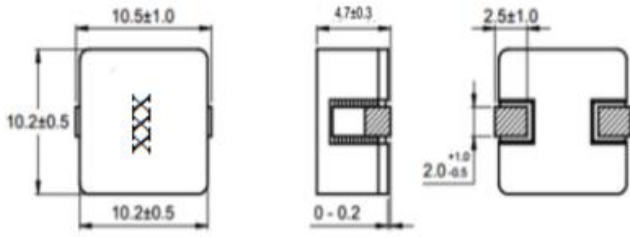
香港瑞德科技有限公司 黄冈市迈翔电子有限公司

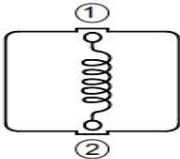
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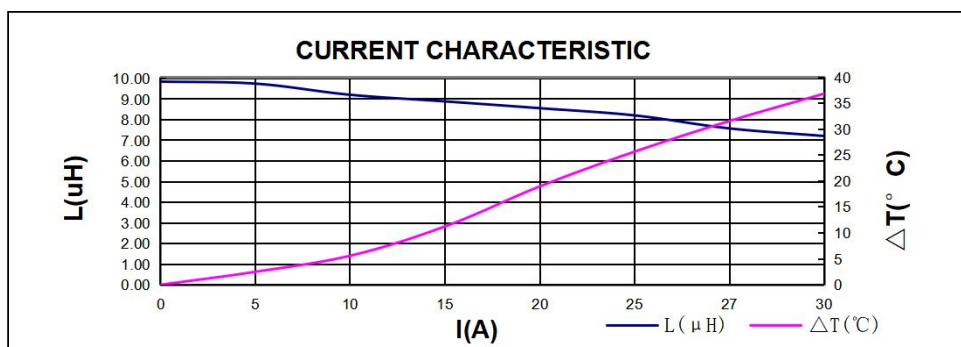
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CUSTOMER		MODEL NO.	MTF1050-100M	REVISION	A0												
FILE NO.		PART NO.		DATE	2021.12.06												
1.PRODUCT DIMENSION				UNIT:mm													
				A	10.5±1.0												
				B	10.2±0.5												
				C	5.0MAX												
2.ELECTRICAL REQUIREMENTS																	
PARAMETER	SPECIFICATION	CONDITION	TEST INSTRUMENTS														
L(uH)	10±20%	100KHz/1.0V	MICROTEST 6377														
DCR(mΩ)	20MAX	At 25℃	TH2512A														
I sat(A)	7.3A TYP L0A*70%	100KHz/1.0V	MICROTEST 6377+6220														
I rms(A)	5.6A TYP ΔT≤40℃	100KHz/1.0V	MICROTEST 6377+6220														
3.MATERIAL LIST																	
<table><tr><td>ITEM</td><td>MATERIAL</td><td>SUPPLIER</td></tr><tr><td>CORE</td><td>DR:10*10*5.0</td><td>YUZHENG/TIANTONG</td></tr><tr><td>WIRE</td><td>0.16x1.8x3.9x13.5ts</td><td></td></tr><tr><td>SOLDER</td><td>TIN-Sn99.95</td><td>QIANDAO/HONGXINGWEI</td></tr></table>						ITEM	MATERIAL	SUPPLIER	CORE	DR:10*10*5.0	YUZHENG/TIANTONG	WIRE	0.16x1.8x3.9x13.5ts		SOLDER	TIN-Sn99.95	QIANDAO/HONGXINGWEI
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WIRE	0.16x1.8x3.9x13.5ts																
SOLDER	TIN-Sn99.95	QIANDAO/HONGXINGWEI															
4.CHARACTERISTICS																	
(1). All test data is based on 25℃ ambient.																	
(2). DC current(A)that will cause an approximate ΔT40℃																	
(3). DC current(A)that will cause L0 to drop approximately 30%Typ																	
(4). Operating temperature range: -40℃~~+125℃																	
(5).The part temperature (ambient + temp rise)should not exceed 125℃ under worst case operating conditions. circuit design, component.PWB trace size and thickness,airflow and other cooling provision all affect the part temperature. Part temperature should be verified in the den application																	
5.SPECIAL REQUEST																	
(1)Lettering 100 on top of the body.																	

COILMX		深圳市迈翔科技有限公司			
CUSTOMER		MODEL NO.	MTF1050-100M	REVISION	A0
FILE NO.		PART NO.		DATE	2021.12.06
6.PRODUCT IDENTIFICATION					
<u>XX</u> <u>XXXX</u> - <u>XXX</u> <u>X</u> <u>X</u> ① ② ③ ④ ⑤ ①、 Product Symbol ②、 Dimensions ③、 Inductance ④、 Tolerance: M±20%, N±30%. ⑤、 Material					
7.ELECTRICAL SCHEMATICS					
					
8.APPLICATION					
(1)Low profile,high current power supplies. (2)Battery powered devices. (3)DC/DC converters in distributed power systems. (5)DC/DC converters for field programmable gate array.					
9.FEATURES					
(1)ROHS compliant. (2)Super low resistance,ultra high current rating. (3)high performance(I sat)realized by metal dust core. (4)Frequency Range:up to 1MHZ.					
10.RECOMMENDED PCB LAYOUT					
			H		
			S		
			M		

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FILE NO.		PART NO.			DATE	2021.12.06	
SORT	ITEM	A	B	C			
PRODUCT & DIMENSION	SPEC	10.5±1.0	10.2±0.5	5.0MAX			
	1	10.01	10.02	4.80			
	2	10.02	10.03	4.81			
	3	10.02	10.02	4.79			
	4	10.03	10.02	4.82			
	5	10.01	10.01	4.81			
	X	10.02	10.02	4.81			
	R	0.02	0.02	0.03			
ELECTRICAL & REQUIREMENTS	ITEM	L(uH)	DCR (mΩ)	I sat(A)	DC BIAS		SHAPE:
	SPEC	10±20%	20MAX	7.3A TYP L0A*70%		I _{rms}	
	1	9.98	17.02	7.14	-28.5%	5.6A TYP ΔT≤40℃	
	2	9.85	17.05	7.15	-27.4%	OK	
	3	10.01	17.00	7.20	-28.1%	OK	
	4	9.98	17.08	7.20	-27.9%	OK	
	5	9.86	17.09	7.16	-27.4%	OK	
	X	9.94	17.05	7.17	-27.8%	OK	
	R	0.16	0.09	0.06	0.01		



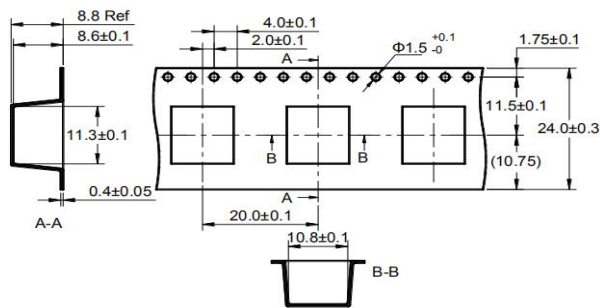
CUSTOMER		MODEL NO.	MTF1050-100M	REVISION	A0
FILE NO.		PART NO.		DATE	2021.12.06
项目Item	规格与需求 Specification and Requirement	测试方法Test Method			
可焊性 Solder ability test	沾锡面积不得小于95%上锡面 Terminals area must have 95% min solder coverage	上锡升温曲线 Solder heat proof: (1) 预热: 160±10℃持续90s Preheating: 160±10℃ for 90 seconds (2) 恒温时段: 245±5℃持续2±0.5s Retention time: 245±5℃ for 2±0.5 seconds			
振动测试 Vibration test	感值变化: 不超过±5% 且无破裂等机械损伤产生 Inductance change: Within±5% Without mechanical damage such as break	(1) 振动频率(10Hz 55Hz 10Hz)60s为一个周期 Vibration frequency: (10Hz to 55Hz to 10Hz) in 60 seconds as a period (2) 振动时间 Vibration time: 三维正交坐标系每个方向振动 (周期) 循环2小时 Period cycled for 2 hours in each of 3 mutual perpendicular directions (3) 振幅 Amplitude: 1.5 mm Max			
冲击测试 Shock test	感值变化: 不超过±5% 且无破裂等机械损伤产生 Inductance change: Within±5% Without mechanical damage such as break	(1) 最大振幅 Peak value: 100G (2) 脉冲波长 Duration of pulse: 11ms (3) 三维正交坐标系每个方向正负方向冲击3次 Times in each positive and negative direction of 3 mutual perpendicular directions			
冷热冲击 Thermal shock	感值变化: 不超过±5% 且无破裂等机械损伤产生 Inductance change: Within±5% Without mechanical damage such as break	(1)重复以上100个循环Repeat 100 cycle as follow (-55±2℃,30±3分钟) 室温5分钟 (-55±2℃,30±3 minutes) Room temperature,5 minutes (+125±2℃,30±3分钟) 室温5分钟 (+125±2℃,30±3 minutes) Room temperature,5 minutes (2)恢复: 测试于标准条件下恢复48+4/-0小时 (参考注释1) Recovery:48+4/-0 hours of recovery under the standard condition after the test. (see Note1)			
耐高温测试 High temperature life test	感值变化: 不超过±5% 且无破裂等机械损伤产生 Inductance change: Within±5% Without mechanical damage such as break	(1)环境条件: 85±2℃ Environment condition : 85±2℃ 应用电流: 额定电流 Applied current: Rated current (2)持续时间: 1000+4/-0 小时 (参考注释1) Duration:1000+4/-0 hours (see Note1)			
耐湿测试 Humidity Resistance	感值变化: 不超过±5% 且无破裂等机械损伤产生 Inductance change: Within±5% Without mechanical damage such as break	(1)环境条件: 60±2℃ Environment condition : 60±2℃ 湿度: 90~95% Humidity:90~95% 应用电流: 额定电流 Applied current: Rated current (2)持续时间: 1000+4/-0 小时 (参考注释1) Duration:1000+4/-0 hours (see Note1)			
低温存放测试Low temperature life test	感值变化: 不超过±5% 且无破裂等机械损伤产生 Inductance change: Within±5% Without mechanical damage such as break	(1)存储温度 Store temperature -55±2℃下存放 1000+4/-0 小时 -55±2℃for total 1000+4/-0 hours			
高温存放测试High temperature life test	感值变化: 不超过±5% 且无破裂等机械损伤产生 Inductance change: Within±5% Without mechanical damage such as break	(1)存储温度 Store temperature +125±2℃下存放 1000+4/-0 小时 +125±2℃for total 1000+4/-0 hours			

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11、包装 Packaging

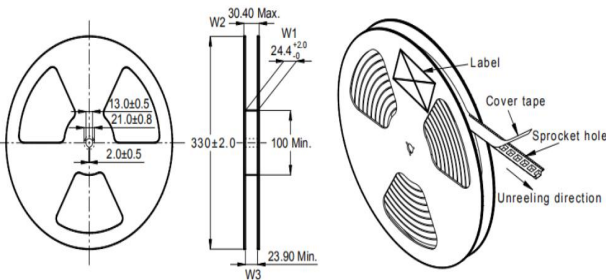
11.1、尺寸 Dimensions

11.1.1 包装料带尺寸 Tape packaging dimensions



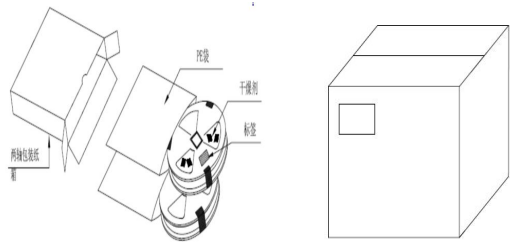
W	A0	B0	K0	P	F	E	D0	P0	T

11.1.2 卷轴尺寸 Reel dimensions



项目	尺寸(mm)
A	330.0 ± 0.5
B	100.0 ± 0.5
C	30.5MAX
G	100MAX

11.1.3 外箱尺寸 Carton dimensions

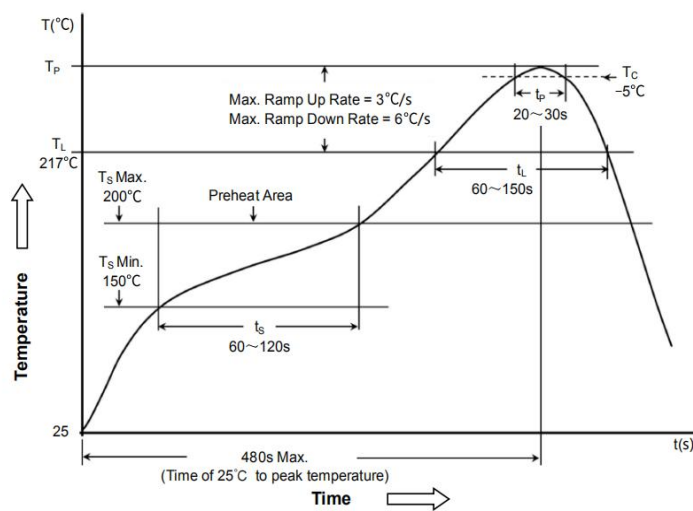


项目	数量 (PCS)
1卷轴	300
1内箱	
1外箱	

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Reflow curve

※ Reflow Profile



1. Reflow Soldering Method

Reflow Soldering	$T_p: 255 \sim 260^{\circ}\text{C}$	Max. 30 seconds (t_p)
	217°C	60~150 seconds
Pre-Heat	$150 \sim 200^{\circ}\text{C}$	60~120 seconds
Time 25°C to peak temperature	8 minutes max.	

2. Soldering iron method : $350 \pm 5^{\circ}\text{C}$ Max. 3 seconds.